

41RIA, 51RIA...F SERIES Fast Power Silicon Controlled Rectifiers

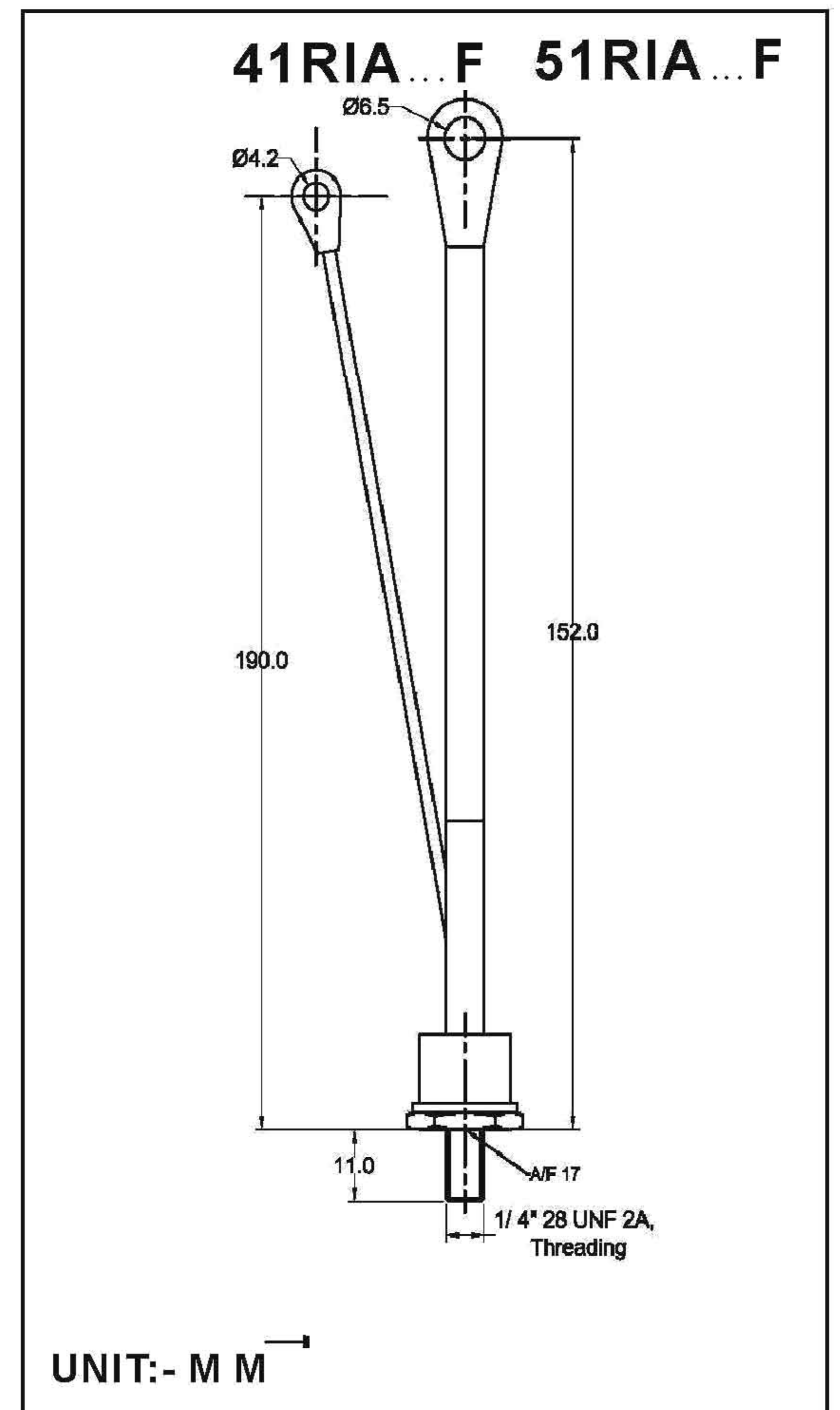
Types : 41RIA10F 41RIA 120F 51RIA10F -51RIA 120F

FEATURES

- ⌘ All diffused series.
- ⌘ High di/dt and dv/dt capabilities.
- ⌘ Reliable blocking at elevated temperature.
- ⌘ High surge current rating.
- ⌘ High I^2t capability.
- ⌘ Excellent dynamic characteristics.

THERMAL MECHANICAL SPECIFICATIONS

R_{thjc}	Maximum thermal resistance junction-to-case DC operation	41RIA	51RIA
		0.4°C/W	0.35°C/W
R_{thcs}	Contact thermal resistance case-to-sink	0.25°C/W	
T_J	Junction operating temp. range	-40°C to +125°C	
T_{stg}	Storage temperature range	-40°C to +125°C	
	Mounting torque (Non-lubricated threads)	0.4 M-Kg min. 0.6 M-Kg max.	
	Approximate weight	30 gms.	
T_q	Max. turn-off time ITM=50A, $di/dt=10A/\mu s$	40μs	
V_{FO}	Max, value of threshold voltage	1V	
r_f	Max, value of forward slop resistance	7.9 mΩ	7.0 mΩ



ELECTRICAL RATINGS

TYPE	41RIA / 51RIA	10	20	40	60	80	100	120
V_{DRM}	Max. repetitive peak off state voltage (V)	100	200	400	600	800	1000	1200
V_{RRM}	Max. repetitive peak reverse voltage (V)	100	200	400	600	800	1000	1200
V_{RSM}	Max. non-repetitive peak reverse voltage (V)	150	300	500	700	900	1100	1300
I_{RM} & I_{DM}	Max. peak reverse & off state current @ rated V_{DRM} & V_{RRM} 125°C -mA	15	15	15	15	15	15	15

FAST SILICON CONTROLLED RECTIFIERS

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ELECTRICAL SPECIFICATIONS

	ON-STATE	41RIA	51RIA	Units	Conditions
$I_{T(RMS)}$	Max. RMS on-state current	63	79	A	
$I_{T(AV)}$	Max. average on-state current	40	50	A	$T_C = 94^{\circ}\text{C}$ max., 180 $^{\circ}\text{C}$ sinusoidal conduction.
I_{TSM}	Max. peak one cycle non-repetitive surge current	700	1000	A	50 Hz half cycle sine wave or 6 ms rectangular pulse.
I^2t	Max. I^2t capability for fusing	2450	5000	A^2s	$t = 10 \text{ ms}$ initial $T_J = 125^{\circ}\text{C}$
V_{TM}	Max. peak on-state voltage	2.4	2.0	V	$T_J = 25^{\circ}\text{C}$, $I_{TM} = \pi \times I_{T(AV)}$
I_H	Max. holding current	200		mA	$T_J = 25^{\circ}\text{C}$, anode supply = 22V, initial $I_T = 2.0\text{A}$
I_L	Max. latching current	400		mA	Anode supply = 6V, resistive load.

BLOCKING

dv/dt	Min. critical rate-of-rise of off-state voltage	500	V/ μs	$T_J = 125^{\circ}\text{C}$. Exponential to 100% rated V_{DRM} For 67% rated V_{DRM}	Zero gate bias voltage gate open circuited.
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SWITCHING

t_d	Typical delay time	40	μs	$T_C = 25^{\circ}\text{C}$, $V_{DM} = \text{rated } V_{DRM}$, $I_{TM} = 10\text{A}$ dc resistive circuit, Gate pulse 10V, 15 Ω source $t_p = 20 \mu\text{s}$
di/dt	Max non-repetitive rate of rise of turned-on current $V_{RRM} = 700\text{-}1400 \text{ V}$ 50 - 600 V	100	A/ μs	$T_C = 125^{\circ}\text{C}$, $V_{DM} = \text{rated } V_{DRM}$, $I_{TM} = 2 \times \text{rated } di/dt$. Gate pulse 20V, 15 Ω , $t_p = 6 \mu\text{s}$, $t_r = 0.1 \mu\text{s}$ max.
t_q	Typical turn-off time	40	μs	$T_C = 125^{\circ}\text{C}$, $I_{TM} = 50\text{A}$, $di/dt = 10 \text{ A}/\mu\text{s}$, V_R during turn-off interval = 50 V min., reapplied $dv/dt = 20 \text{ V}/\mu\text{s}$ linear to rated V_{DRM} Gate bias : 0V, 100 Ω

TRIGGERING

P_{GM}	Max. peak gate power	10	W	$t_p \leq 5\text{ms}$
$P_{G(AV)}$	Max. average gate power	2.5	W	
I_{GM}	Max. peak positive gate current	2.5	A	
$+V_{GM}$	Max. peak positive gate voltage	20	V	
$-V_{GM}$	Max. peak negative gate voltage	10	V	
I_{GT}	Max. required DC gate current to trigger	100	mA	$T_J = 25^{\circ}\text{C}$ Max. required gate trigger current is the lowest value which will trigger all units with + 6V anode-to-cathode.
V_{GT}	Max. required DC gate voltage to trigger	2.5	V	$T_J = 25^{\circ}\text{C}$ Max. required gate trigger voltage is the lowest value which will trigger all units with + 6V anode-to-cathode.
V_{GD}	Max. DC gate voltage not to trigger	0.2	V	$T_J = 125^{\circ}\text{C}$ Max. gate current or voltage not to trigger is the maximum value which will not trigger any unit with rated V_{DRM} anode-to-cathode.
I_{GD}	Max. DC gate current not to trigger	5.0	mA	$T_J = 125^{\circ}\text{C}$ $V_{DRM} = \text{rated voltage}$

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ORDER INFORMATION TABLE

41/51	RIA	40	M	F
①	②	③	④	⑤

- ①

-

Current Code
40/50 - without external lead
with external lead
- ②

-

RIA - Essential part number
- ③

-

Voltage Rating (See table)
- ④

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Non Stud 1/4" 28UNF 2A Threading
M - Stud M8 x 1.25P Metric Threading
- ⑤

-

F - Inverter grade (fast)

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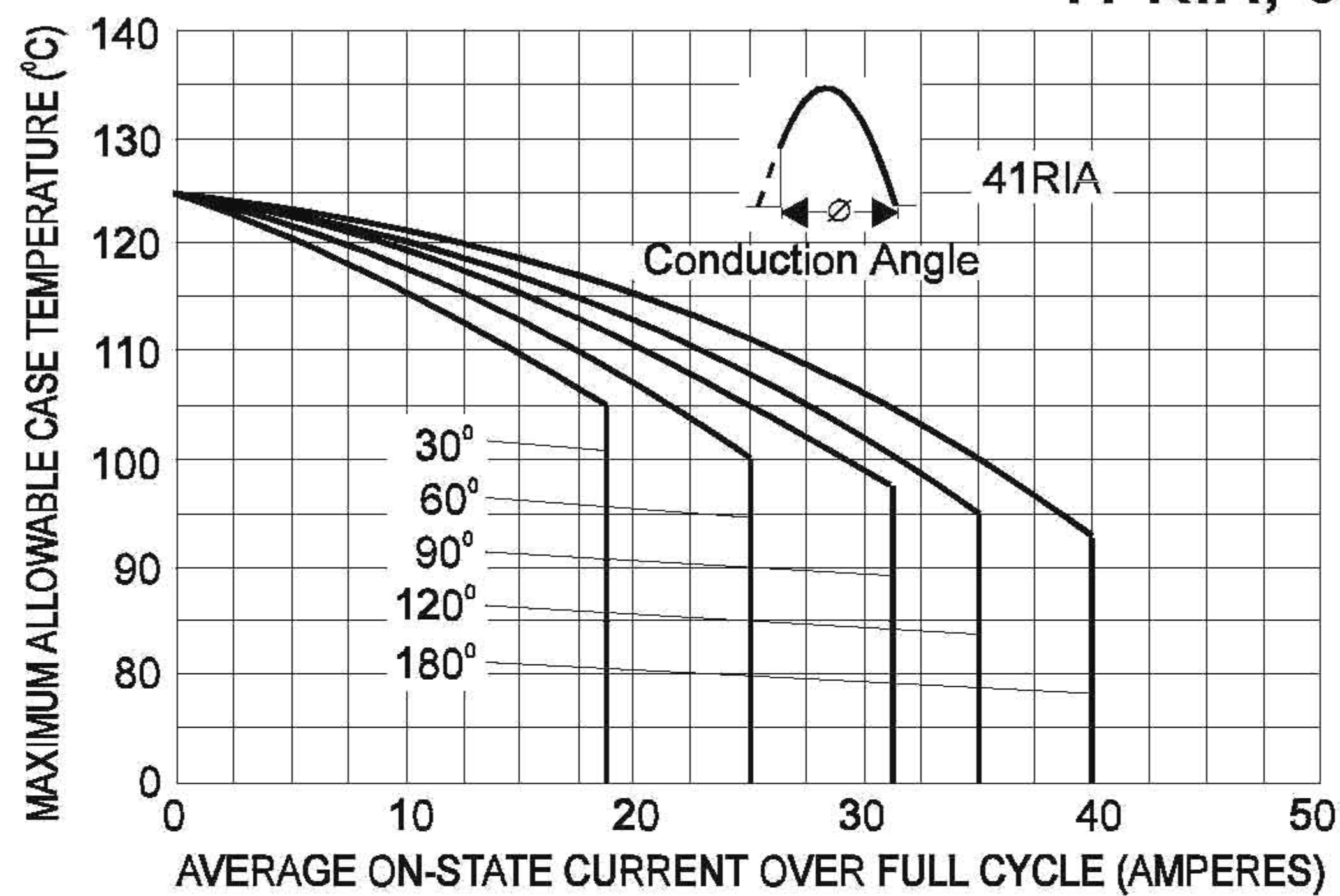


Fig. 1 - On-state Current Vs. Case Temperature (Sinusoidal Current Waveform, 50 to 400 Hz)

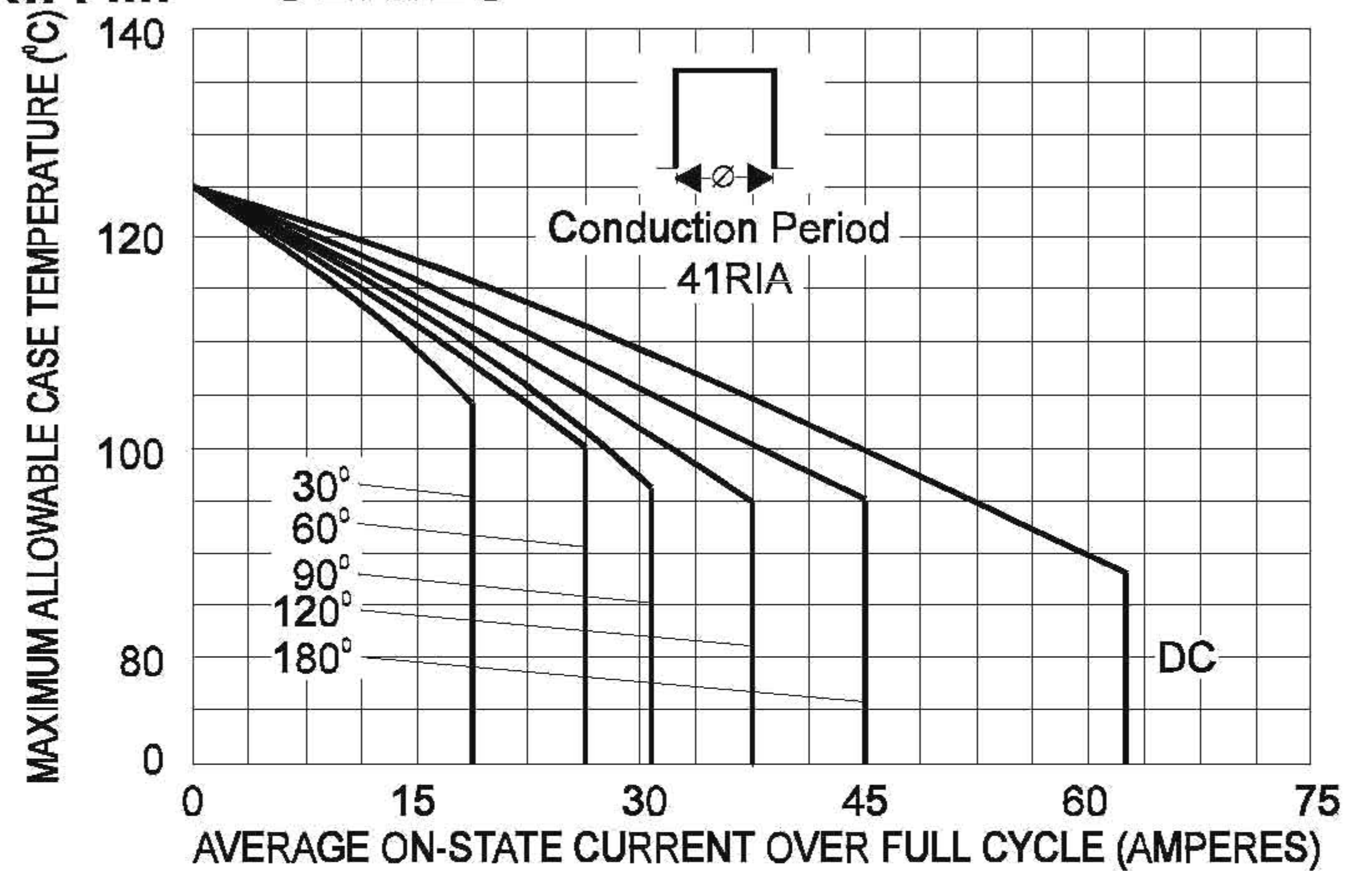


Fig. 2 - On-state Current Vs. Case Temperature (Rectangular Current Waveform, 50 to 400 Hz)

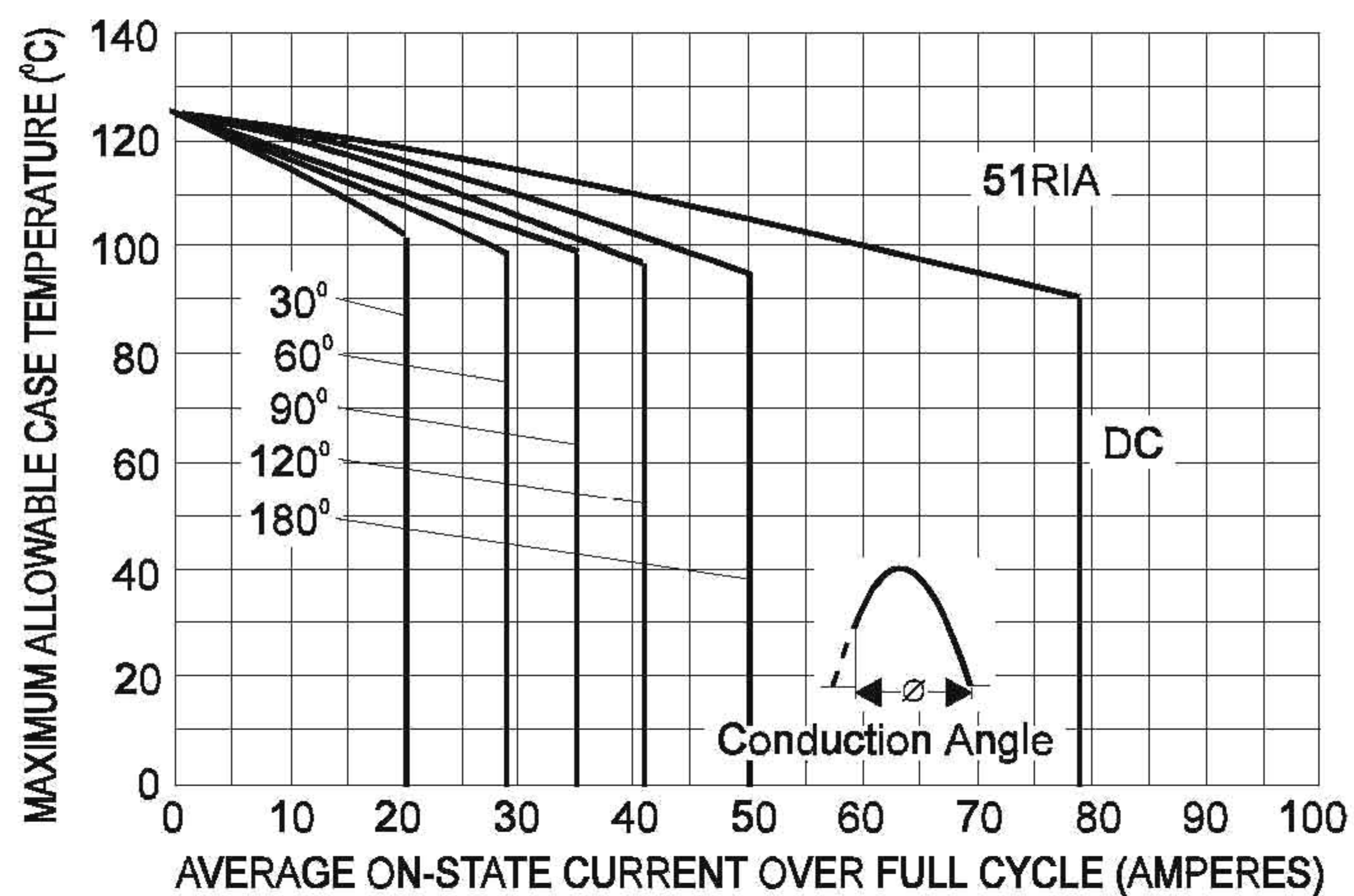


Fig. 3 - On-state Current Vs. Case Temperature (Sinusoidal Current Waveform, 50 to 400 Hz)

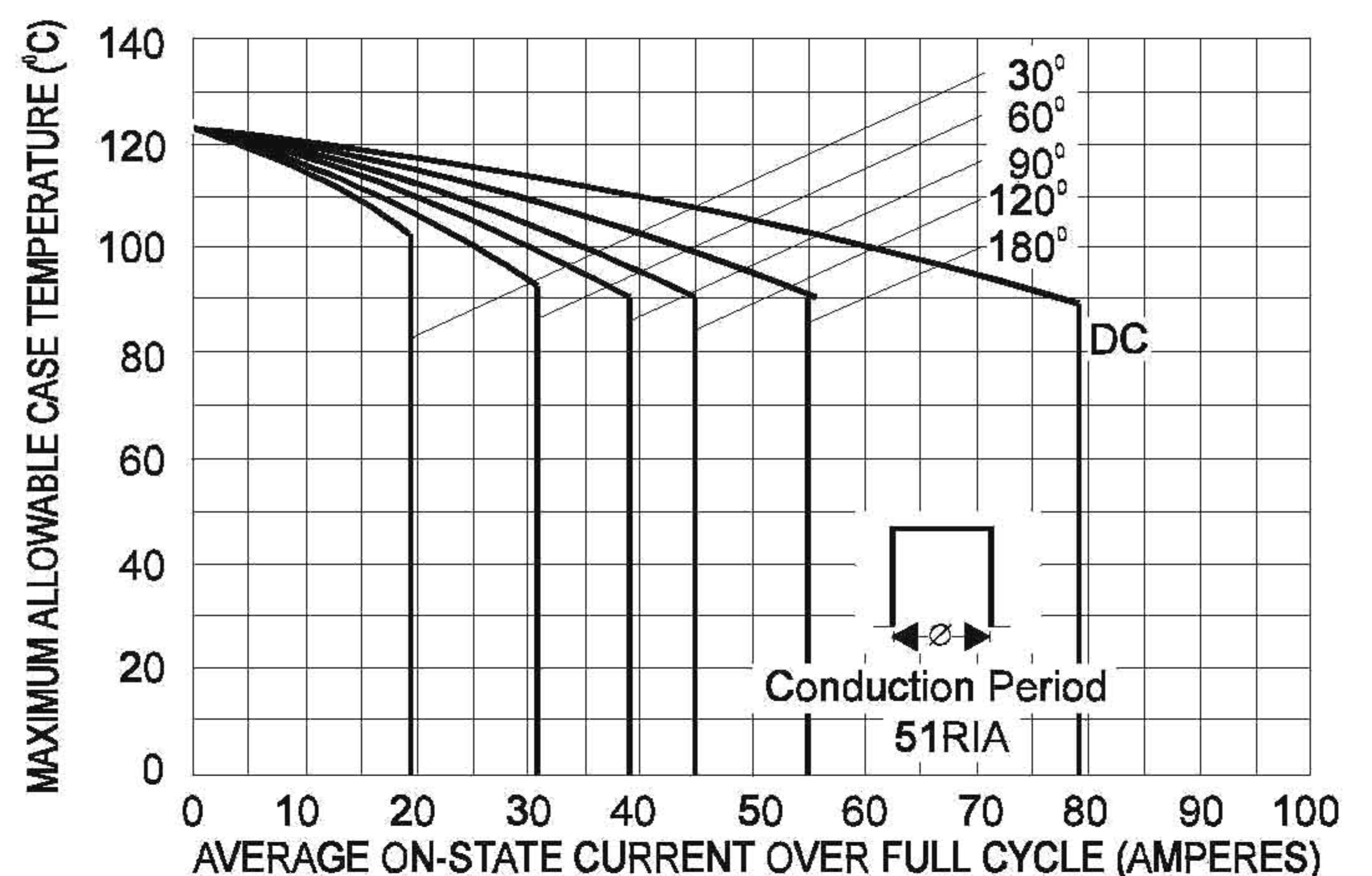


Fig. 4 - On-state Current Vs. Case Temperature (Rectangular Current Waveform, 50 to 400 Hz)

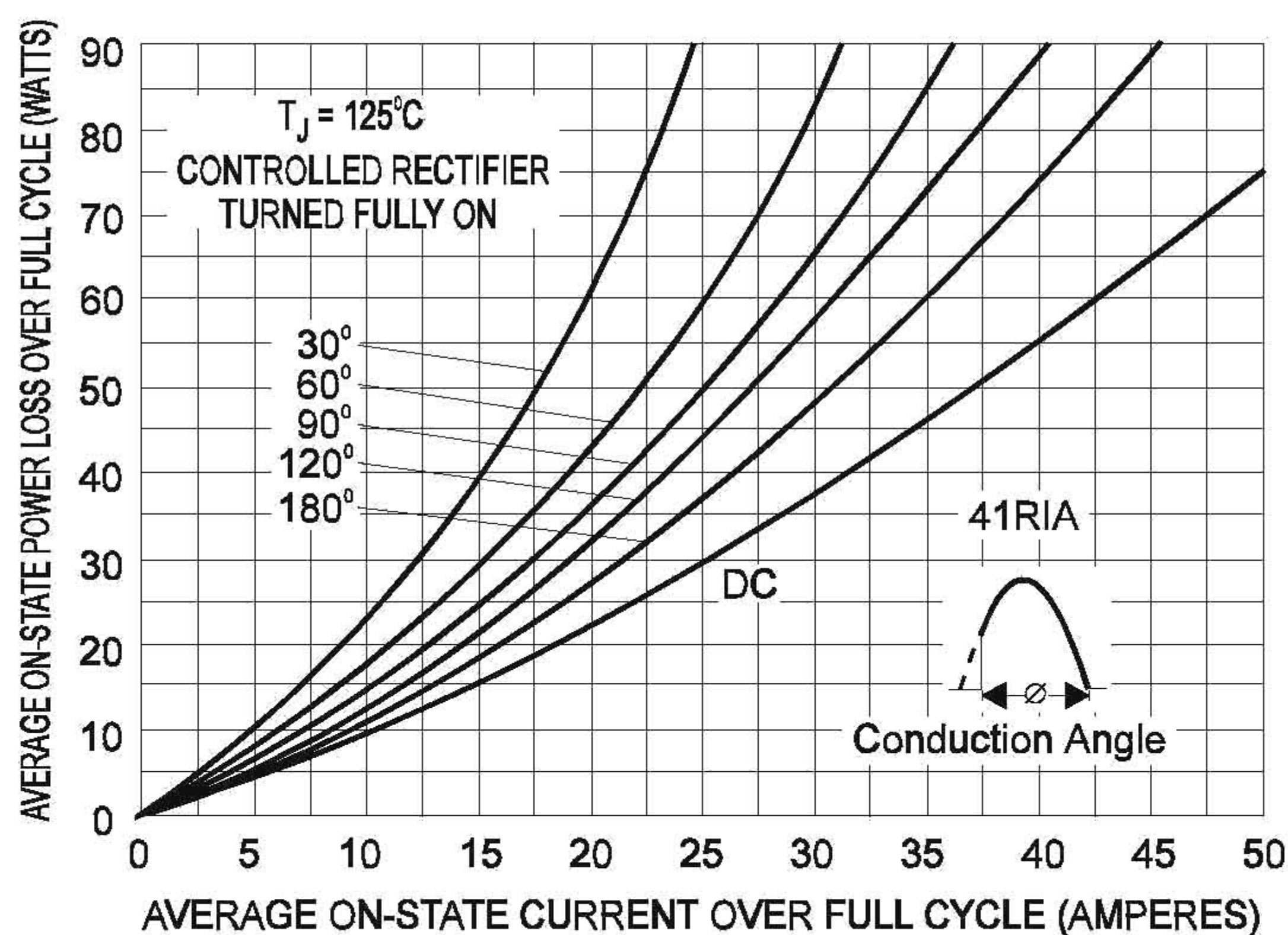


Fig. 5 - Maximum Low-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)

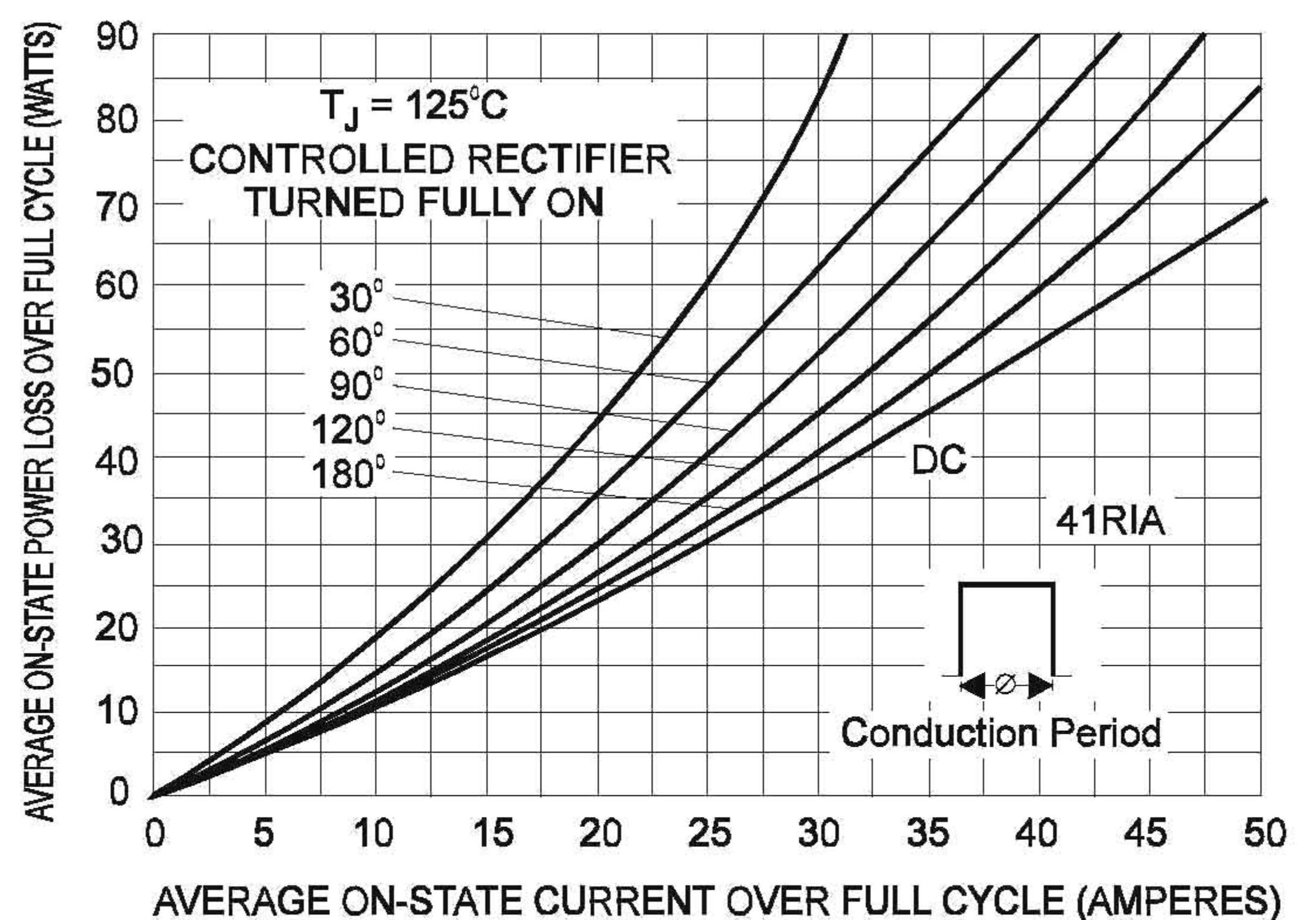


Fig. 6 - Maximum Low-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)

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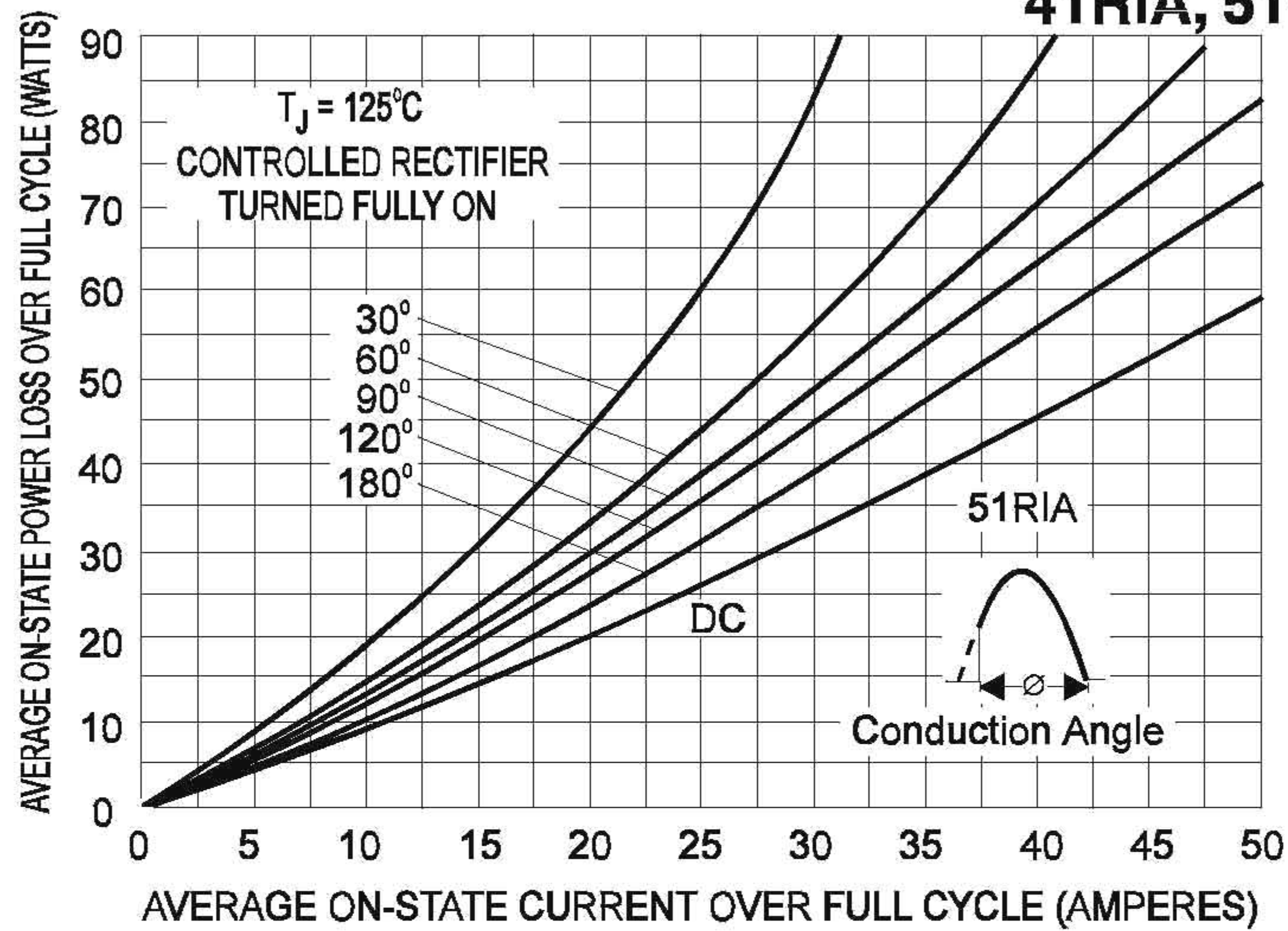


Fig. 7 - Maximum Low-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)

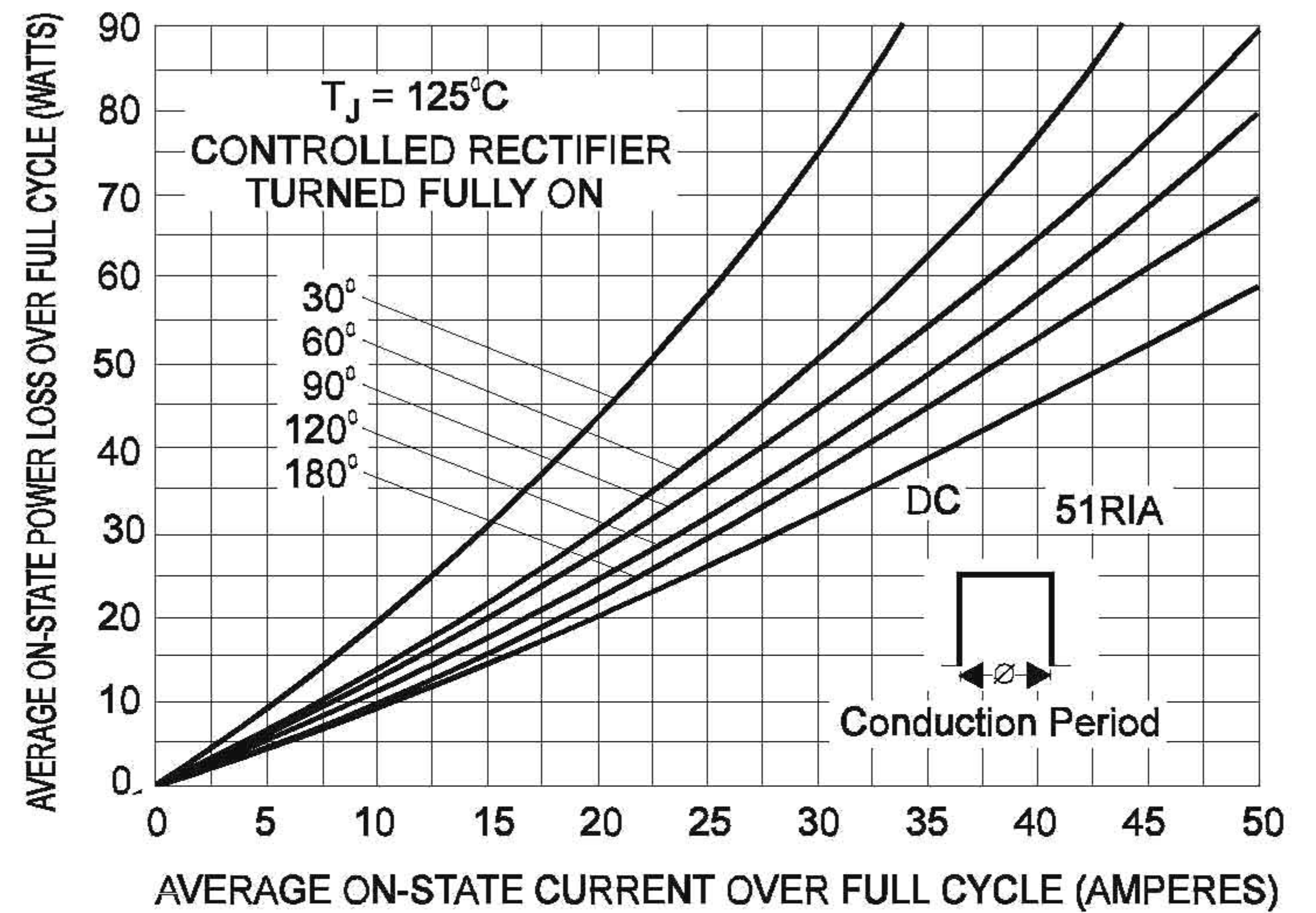


Fig. 8 - Maximum Low-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)

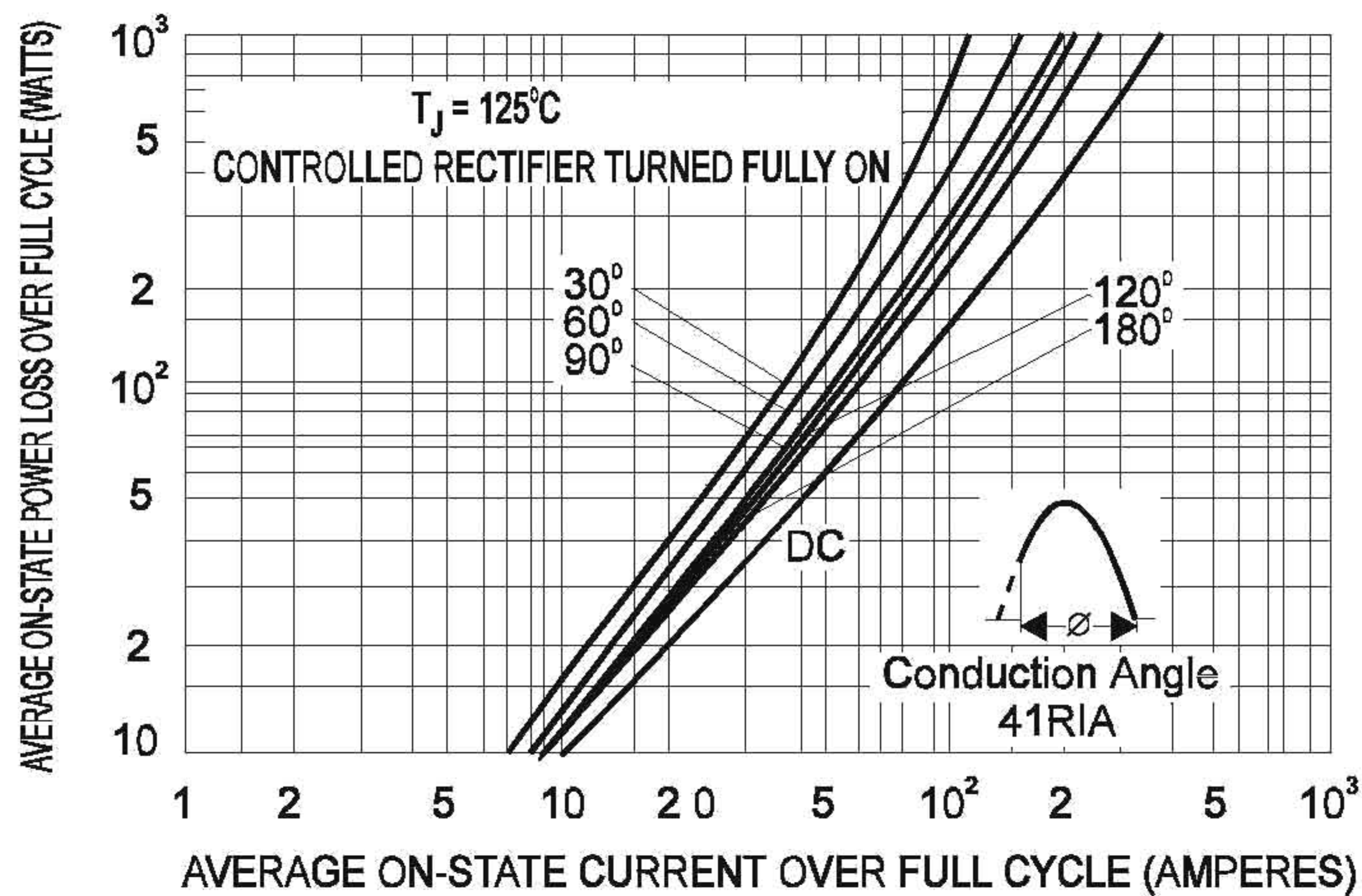


Fig. 9 - Maximum High-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)

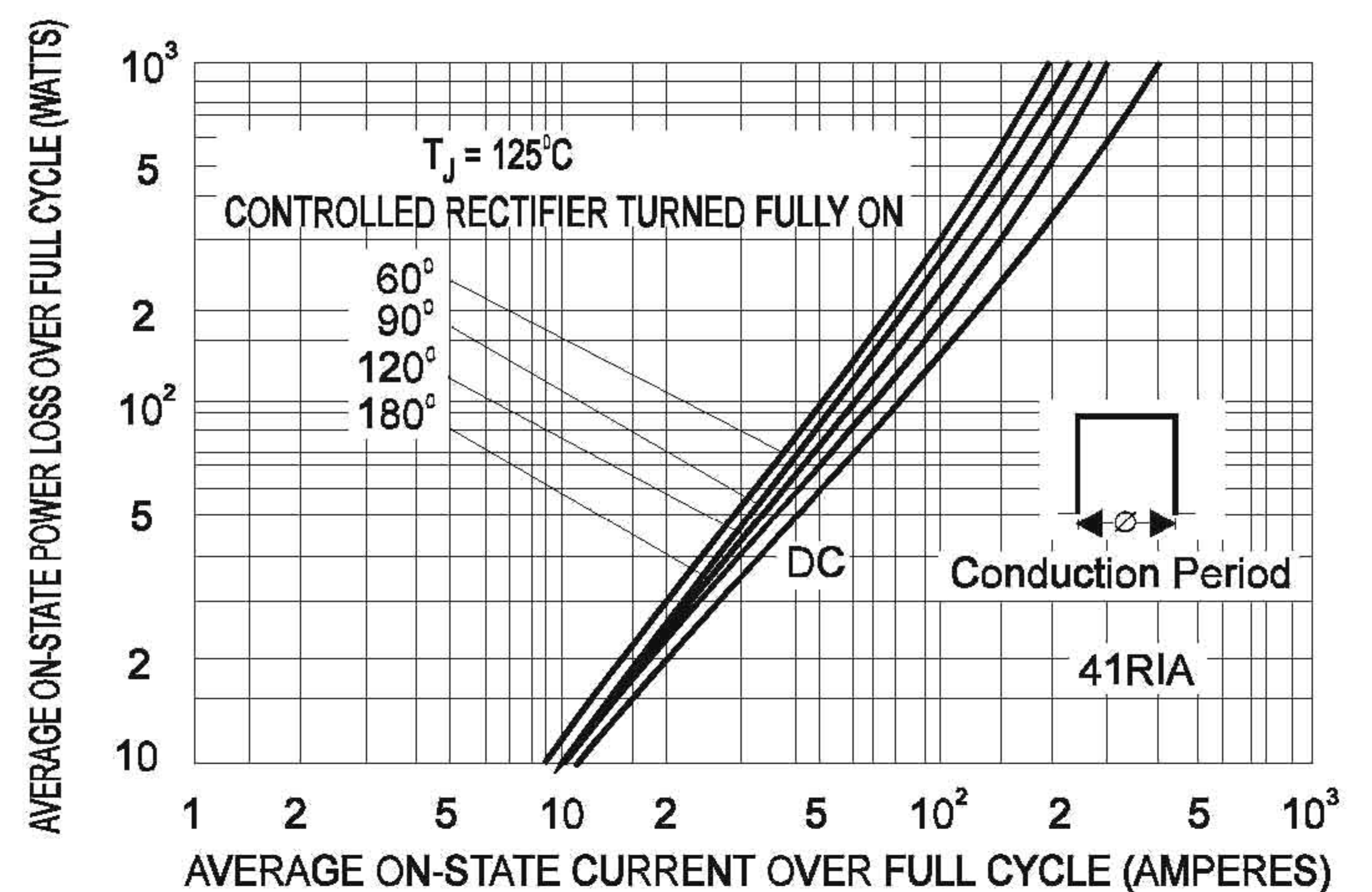


Fig. 10 - Maximum High-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)

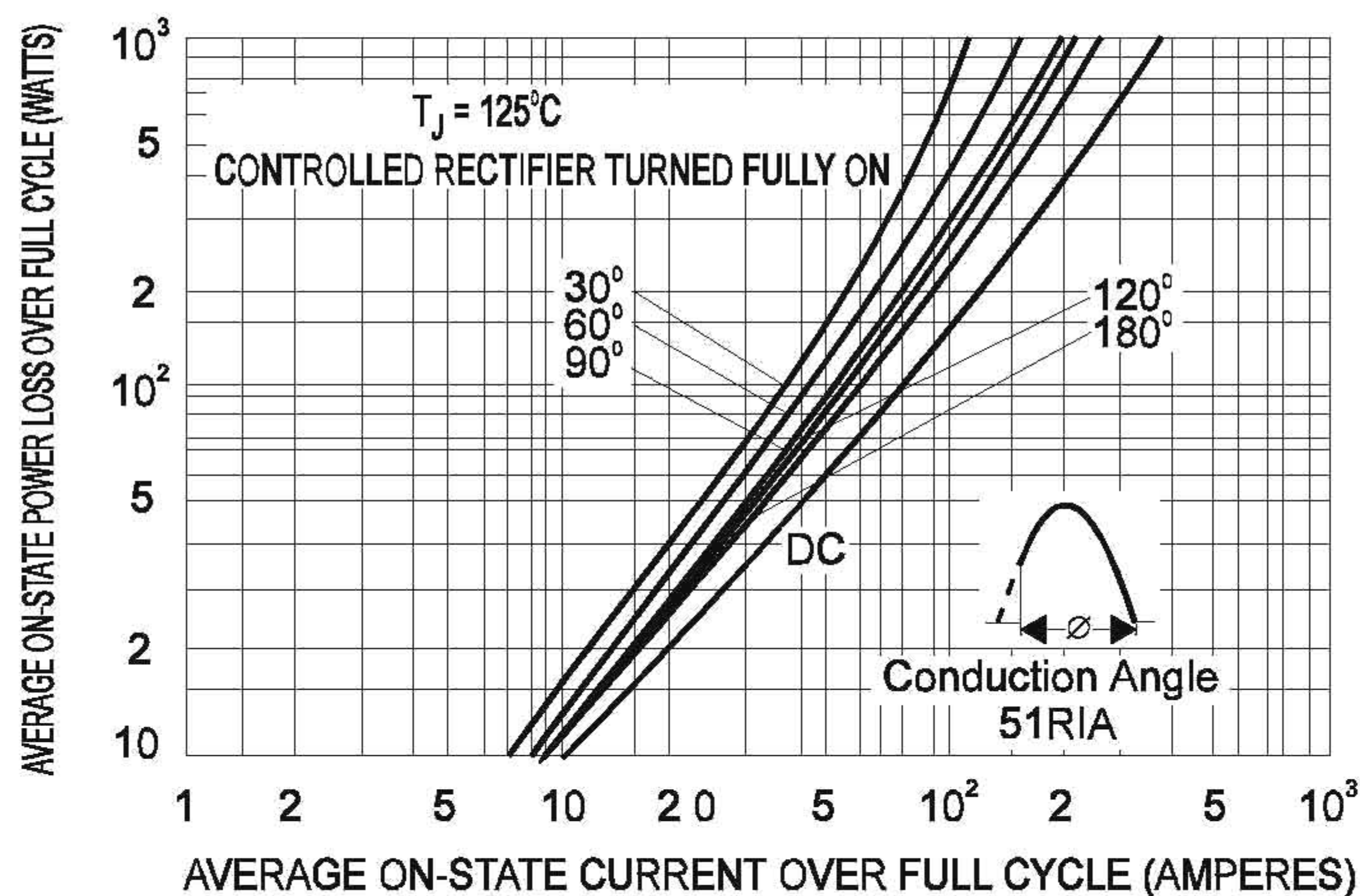


Fig. 11 - Maximum High-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)

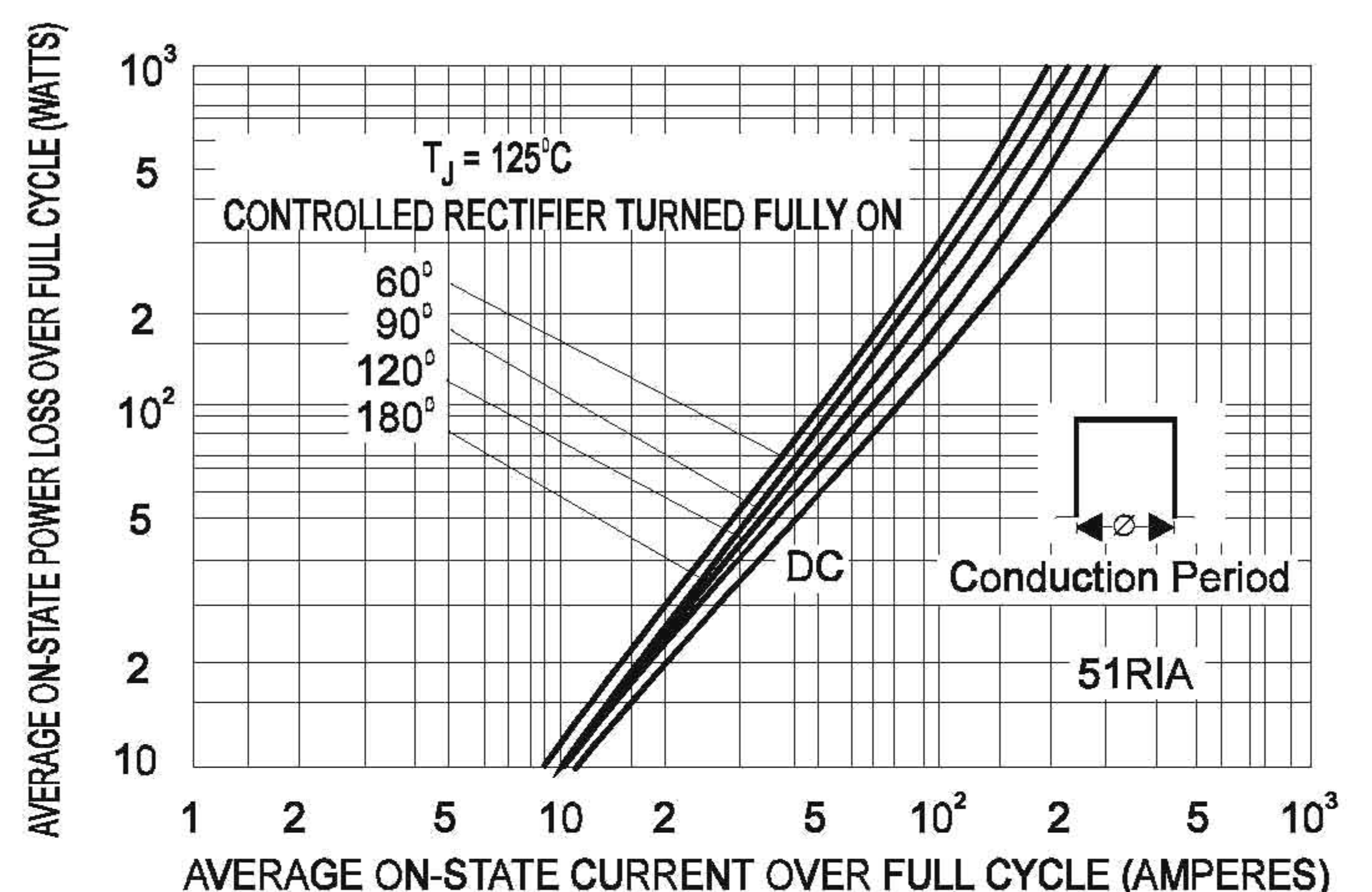


Fig. 12 - Maximum High-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)

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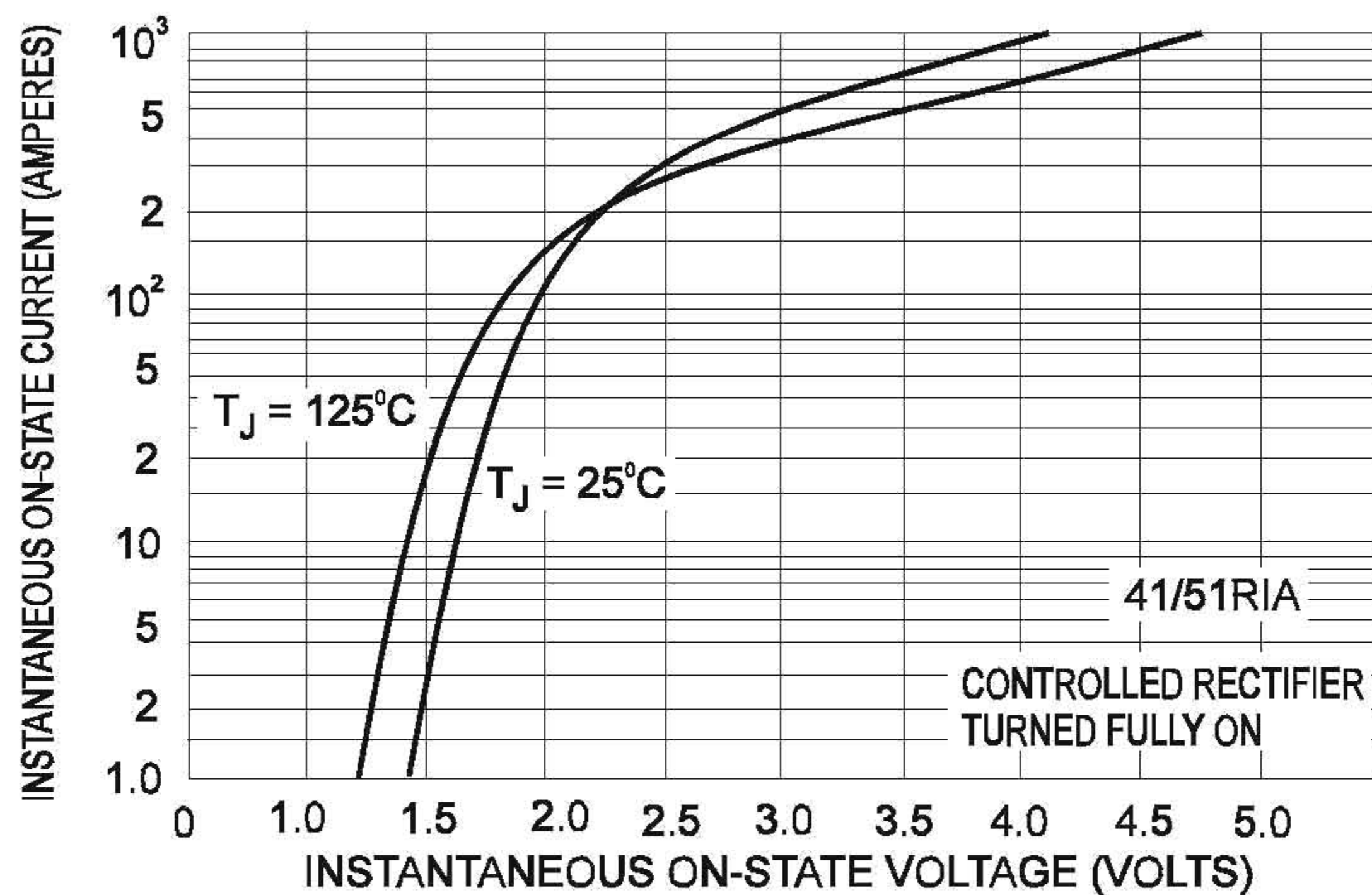


Fig. 13 - Maximum On-state Voltage Vs. Current

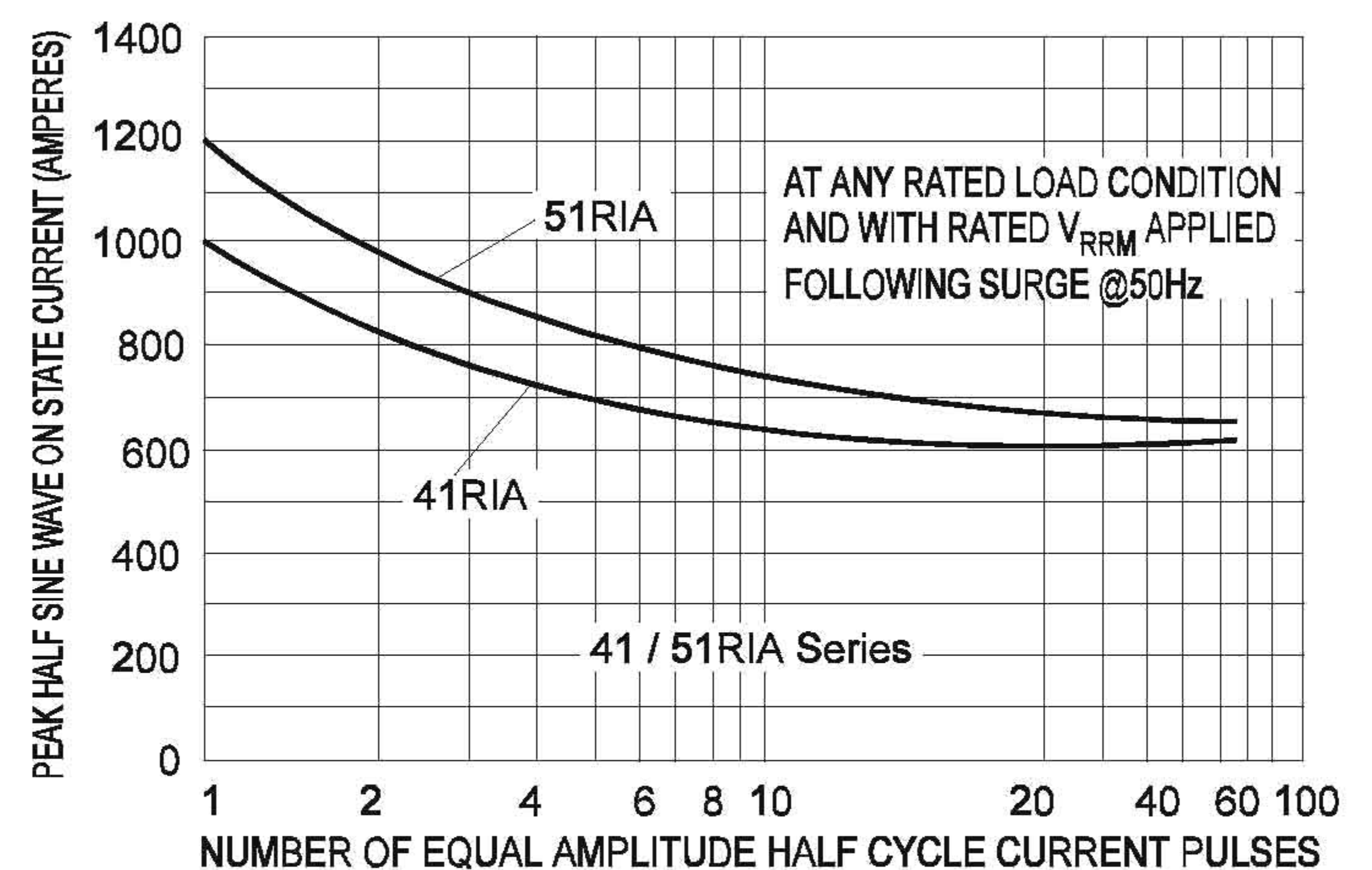


Fig. 14 - Maximum Non-Repetitive Surge Current Vs. Number of Current Pulses

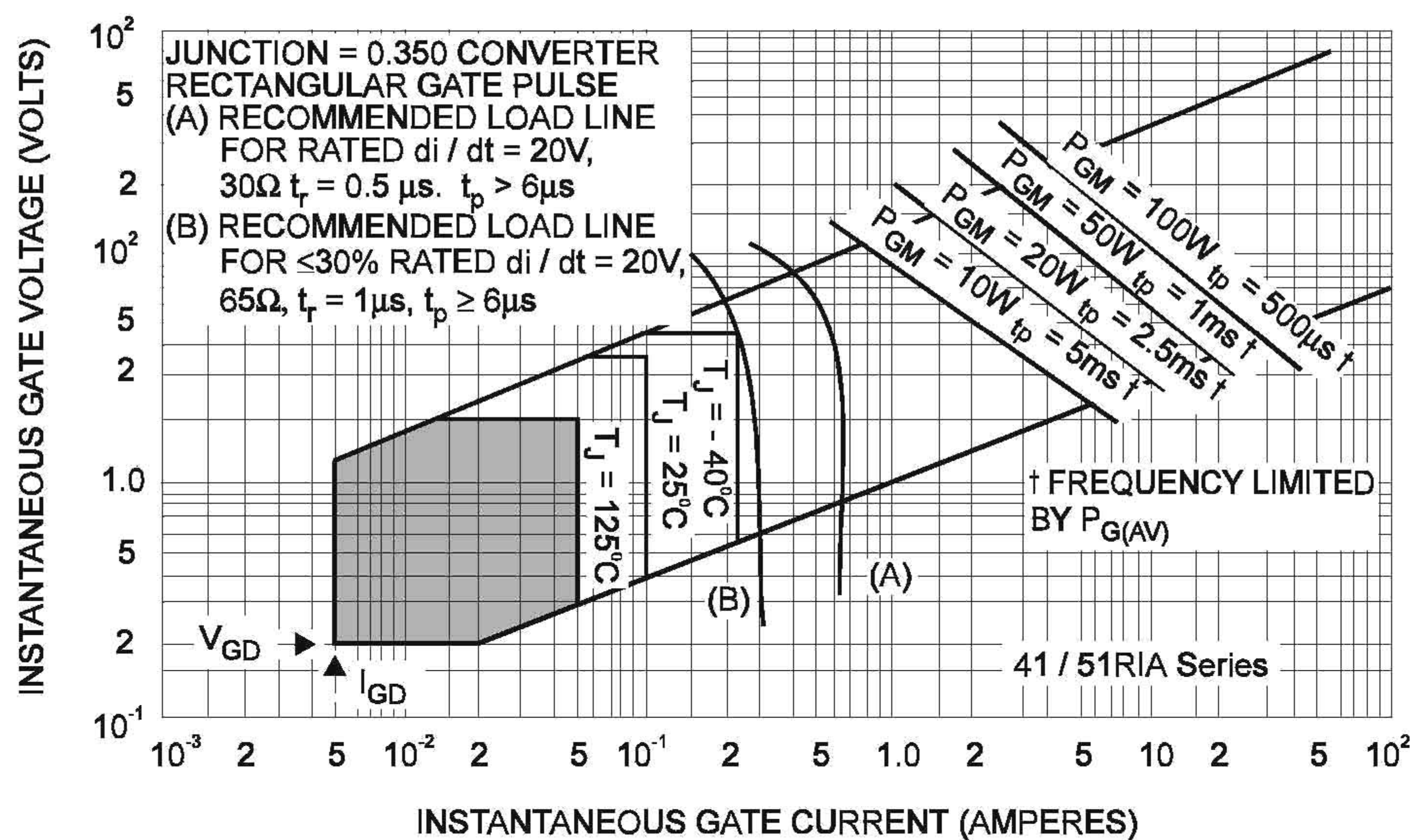


Fig. 15 - Gate Characteristics

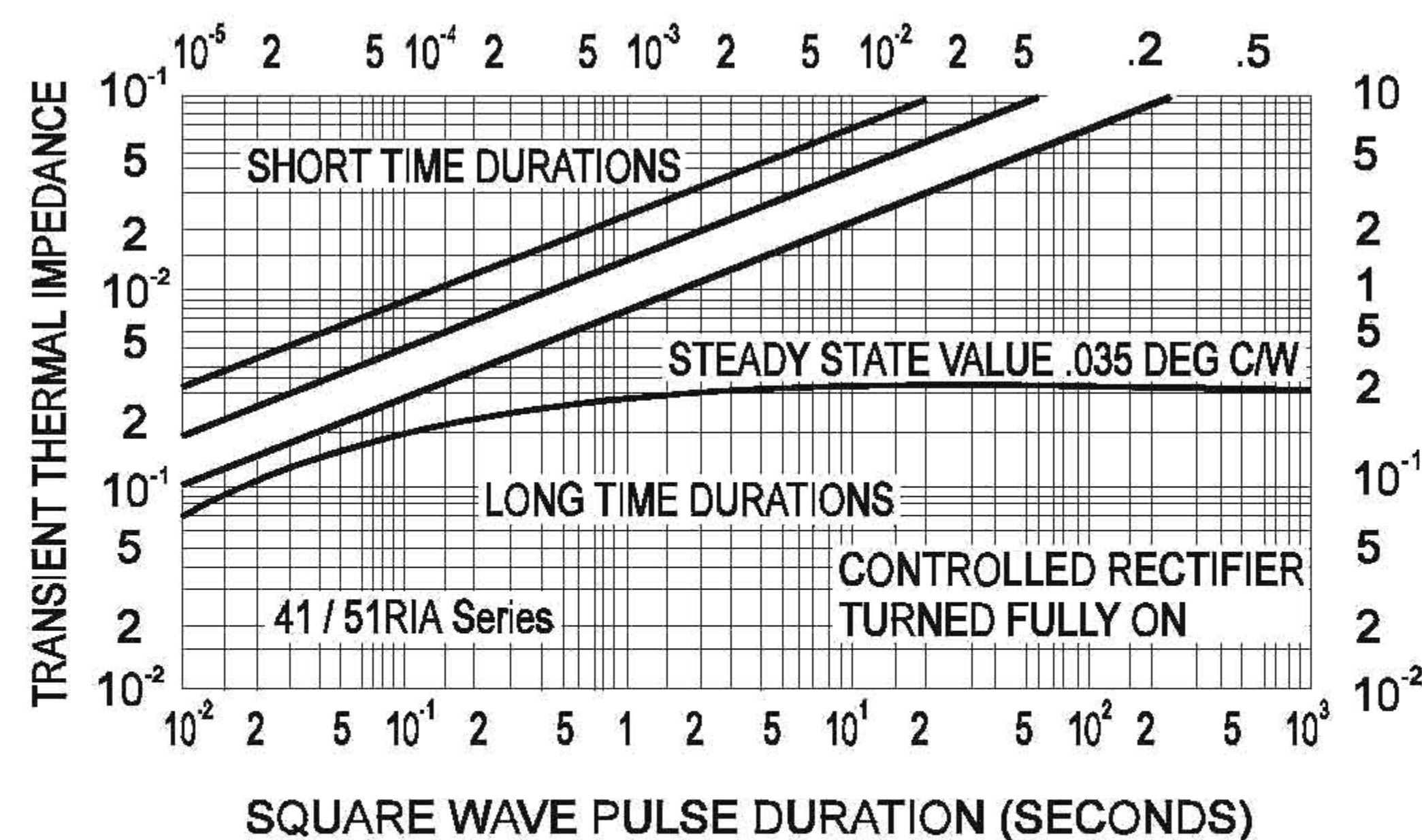


Fig. 16 - Maximum Transient Thermal Impedance, Junction To Case Vs Square Wave Pulse Duration